

Abstract of the Disclosure

An integrated circuit transformer. A substrate supporting multiple layers of materials of an integrated circuit is provided with a first metallization layer comprising a first set of turns of a primary winding of a transformer, and a second set of turns of a secondary winding of the transformer. A insulation layer is deposited over the first metallization layer, and a second metallization layer bearing a second set of turns of the primary winding, and an optional third set of turns of a second secondary winding. A via connection connects one end of the first set of turns of the primary winding to the second turns of the primary winding located on the second metallization layer. The result is a transformer structure where the primary winding is provided on multiple layers and each secondary winding is confined to a single layer.